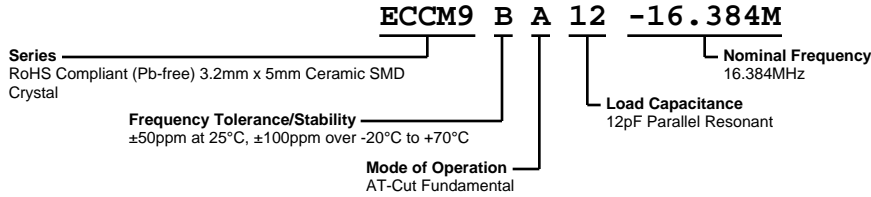


# ECCM9BA12-16.384M



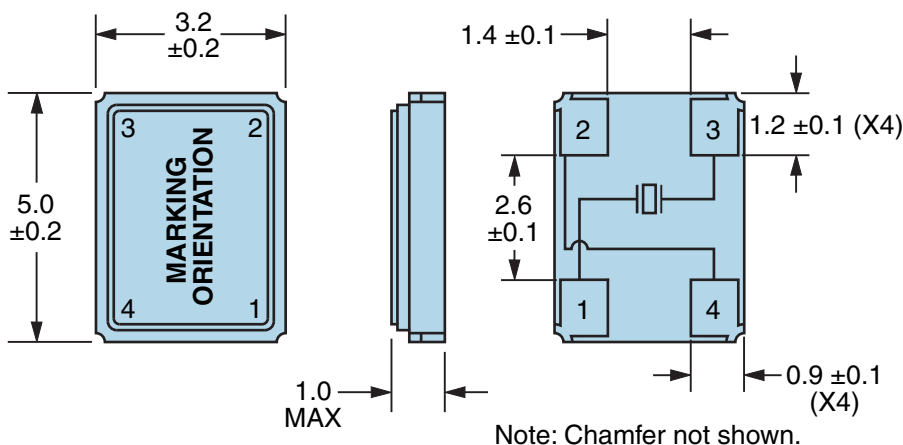
## ELECTRICAL SPECIFICATIONS

Nominal Frequency	16.384MHz
Frequency Tolerance/Stability	±50ppm at 25°C, ±100ppm over -20°C to +70°C
Aging at 25°C	±3ppm/Year Maximum
Load Capacitance	12pF Parallel Resonant
Shunt Capacitance (C0)	7pF Maximum
Equivalent Series Resistance	60 Ohms Maximum
Mode of Operation	AT-Cut Fundamental
Drive Level	100µWatts Maximum, 10µWatts Correlation
Crystal Cut	AT-Cut
Spurious Response	>3dB from Fo to Fo+5000ppm
Storage Temperature Range	-40°C to +125°C
Insulation Resistance	500 Megaohms Minimum at 100Vdc

## ENVIRONMENTAL & MECHANICAL SPECIFICATIONS

ESD Susceptibility	MIL-STD-883, Method 3015, Class 1, HBM: 1500V
Fine Leak Test	MIL-STD-883, Method 1014, Condition A
Flammability	UL94-V0
Gross Leak Test	MIL-STD-883, Method 1014, Condition C
Mechanical Shock	MIL-STD-883, Method 2002, Condition B
Moisture Resistance	MIL-STD-883, Method 1004
Moisture Sensitivity	J-STD-020, MSL 1
Resistance to Soldering Heat	MIL-STD-202, Method 210, Condition K
Resistance to Solvents	MIL-STD-202, Method 215
Solderability	MIL-STD-883, Method 2003
Temperature Cycling	MIL-STD-883, Method 1010, Condition B
Vibration	MIL-STD-883, Method 2007, Condition A

## MECHANICAL DIMENSIONS (all dimensions in millimeters)



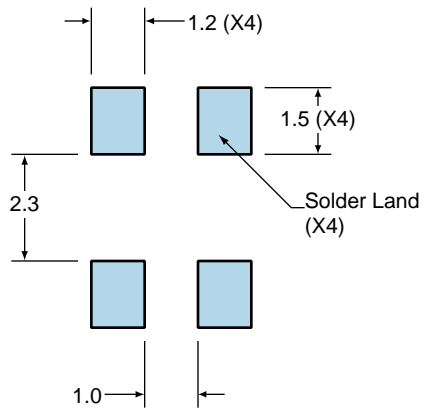
PIN	CONNECTION
1	Crystal
2	Cover/Ground
3	Crystal
4	Cover/Ground

LINE	MARKING
1	<b>E16.38</b> E=Ecliptek
2	<b>XXXXX</b> XXXXX=Ecliptek Manufacturing Identifier

# ECCM9BA12-16.384M

## Suggested Solder Pad Layout

All Dimensions in Millimeters



All Tolerances are  $\pm 0.1$

## Recommended Solder Reflow Methods



### High Temperature Infrared/Convection

<b><math>T_s \text{ MAX}</math> to <math>T_L</math> (Ramp-up Rate)</b>	$3^\circ\text{C/second}$ Maximum
<b>Preheat</b>	
- Temperature Minimum ( $T_s \text{ MIN}$ )	$150^\circ\text{C}$
- Temperature Typical ( $T_s \text{ TYP}$ )	$175^\circ\text{C}$
- Temperature Maximum ( $T_s \text{ MAX}$ )	$200^\circ\text{C}$
- Time ( $t_s \text{ MIN}$ )	60 - 180 Seconds
<b>Ramp-up Rate (<math>T_L</math> to <math>T_p</math>)</b>	$3^\circ\text{C/second}$ Maximum
<b>Time Maintained Above:</b>	
- Temperature ( $T_L$ )	$217^\circ\text{C}$
- Time ( $t_L$ )	60 - 150 Seconds
<b>Peak Temperature (<math>T_p</math>)</b>	$260^\circ\text{C}$ Maximum for 10 Seconds Maximum
<b>Target Peak Temperature (<math>T_p \text{ Target}</math>)</b>	$250^\circ\text{C} \pm 5^\circ\text{C}$
<b>Time within <math>5^\circ\text{C}</math> of actual peak (<math>t_p</math>)</b>	20 - 40 seconds
<b>Ramp-down Rate</b>	$6^\circ\text{C/second}$ Maximum
<b>Time <math>25^\circ\text{C}</math> to Peak Temperature (t)</b>	8 minutes Maximum
<b>Moisture Sensitivity Level</b>	Level 1

## Recommended Solder Reflow Methods



### Low Temperature Infrared/Convection 240°C

<b><math>T_S</math> MAX to <math>T_L</math> (Ramp-up Rate)</b>	5°C/second Maximum
<b>Preheat</b>	
- Temperature Minimum ( $T_S$ MIN)	N/A
- Temperature Typical ( $T_S$ TYP)	150°C
- Temperature Maximum ( $T_S$ MAX)	N/A
- Time ( $t_s$ MIN)	60 - 120 Seconds
<b>Ramp-up Rate (<math>T_L</math> to <math>T_P</math>)</b>	5°C/second Maximum
<b>Time Maintained Above:</b>	
- Temperature ( $T_L$ )	150°C
- Time ( $t_L$ )	200 Seconds Maximum
<b>Peak Temperature (<math>T_P</math>)</b>	240°C Maximum
<b>Target Peak Temperature (<math>T_P</math> Target)</b>	240°C Maximum 1 Time / 230°C Maximum 2 Times
<b>Time within 5°C of actual peak (<math>t_p</math>)</b>	10 seconds Maximum 2 Times / 80 seconds Maximum 1 Time
<b>Ramp-down Rate</b>	5°C/second Maximum
<b>Time 25°C to Peak Temperature (t)</b>	N/A
<b>Moisture Sensitivity Level</b>	Level 1

### Low Temperature Manual Soldering

185°C Maximum for 10 seconds Maximum, 2 times Maximum.

### High Temperature Manual Soldering

260°C Maximum for 5 seconds Maximum, 2 times Maximum.